



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

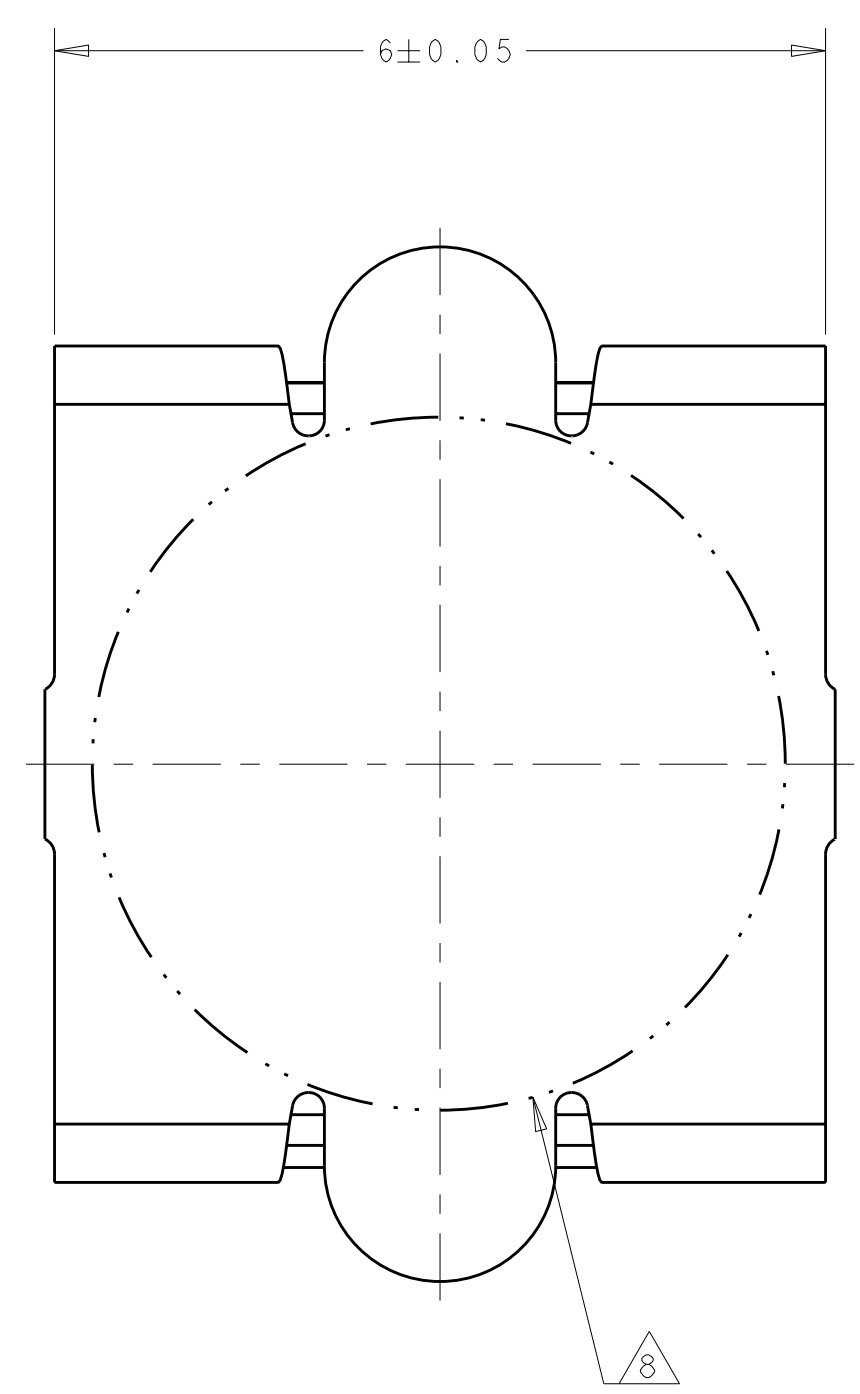
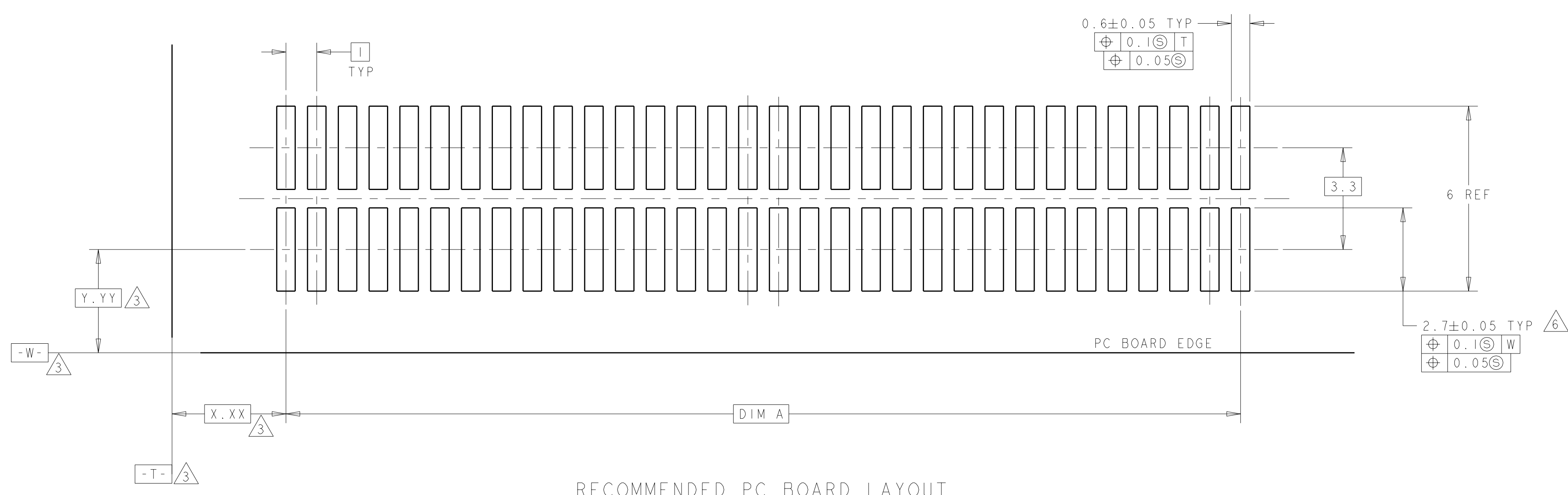
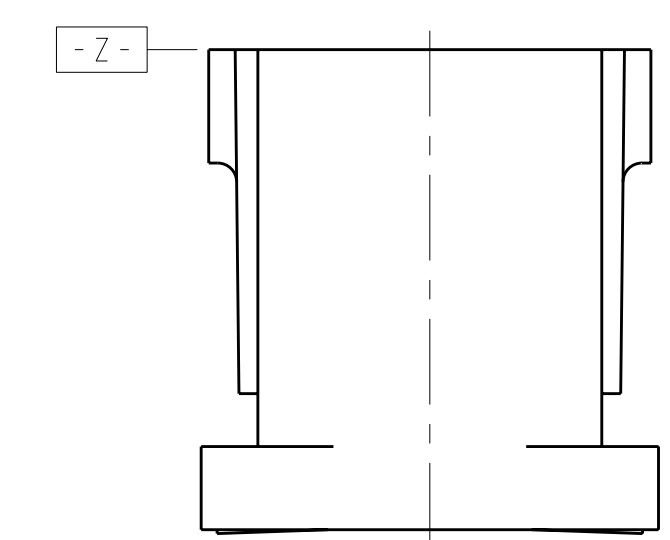
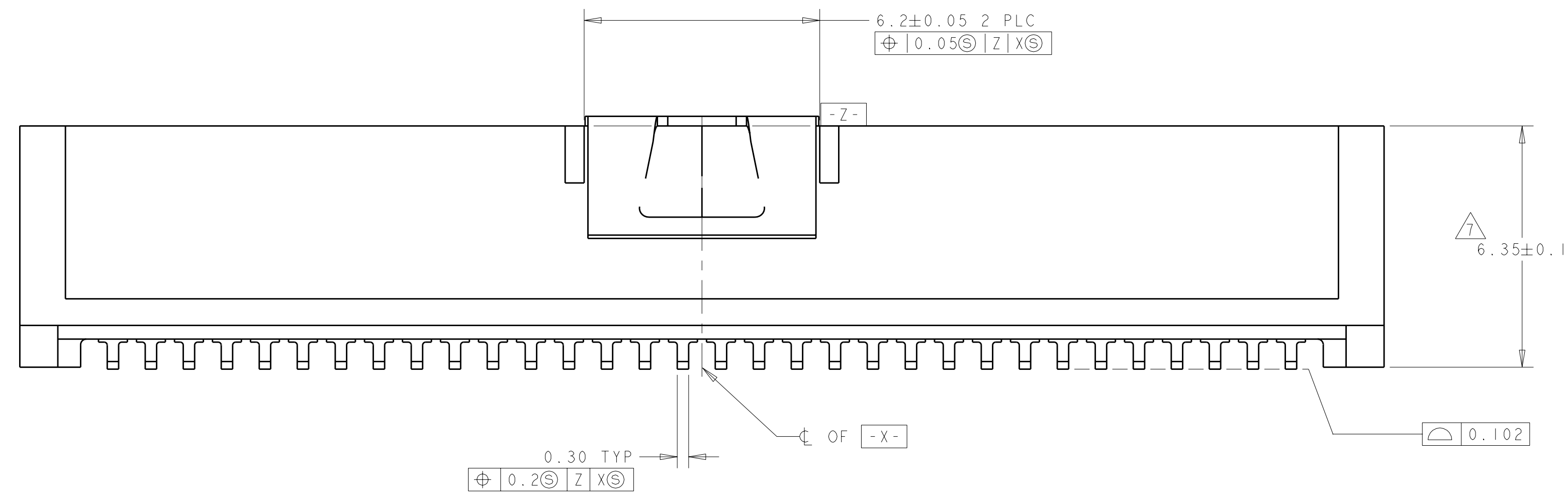
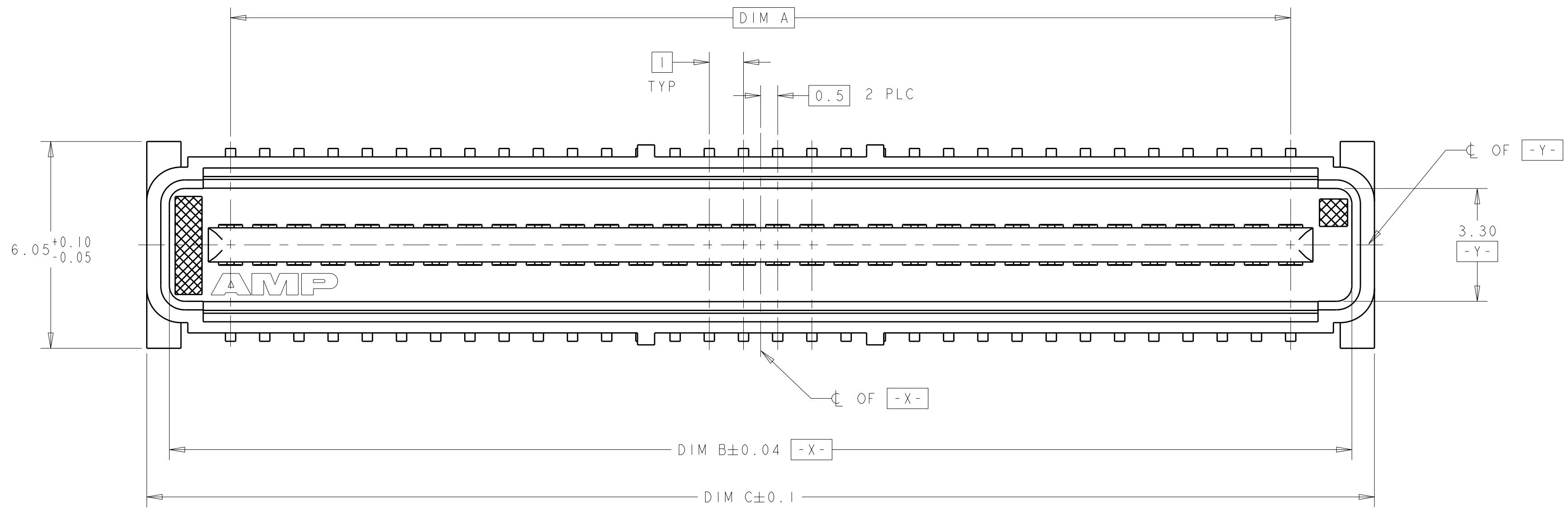
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LOC	DIST	REV	DATE	BY	CHK	APP'D
AD	00	0	30SEP2004	BC	RW	
		A	16SEP2005	BC	RW	
		B	10JUL2008	DH	DB	



VACUUM COVER

- 1. HOUSING MATERIAL: LIQUID CRYSTAL POLYMER COLOR: BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
- 2. CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN.
- 3. DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
- 4. PACKAGED IN TAPE ON REEL PER EIA-481.
- 5. VACUUM COVER DESIGNED FOR 4mm DIA. NOZZLE. VACUUM COVER TO BE REMOVED AFTER SOLDERING. VACUUM COVER REMOVED FROM SOME VIEWS FOR DIMENSIONAL CLARITY.
- 6. SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.7 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
- 7. REFERRED TO AS DIM N IN EIA 700AAAB SPECIFICATION.
- 8. 5.5 MIN DIAMETER TARGET AREA FOR VACUUM PICK-UP.
- 9. CONTACT FINISH: 0.00381 MINIMUM MATTE TIN PER ASTM B 545 ON SOLDER AREA, 0.00127 MINIMUM GOLD PER ASTM B 488 ON MATING AREA, BOTH OVER 0.00127 MINIMUM NICKEL PER SAE-AMS-QQ-N-290 ON ENTIRE CONTACT.

REV	DATE	BY	CHK	APP'D	DESCRIPTION
9	45.9	44.58	41		5120528-2
8	35.9	34.58	31		5120528-1
7	45.9	44.58	41		5120528-2
6	35.9	34.58	31		5120528-1

FINISH	DIM C	DIM B	DIM A	MATING CONNECTOR	STACK HGTS	POS	PART NO
9	45.9	44.58	41	5120528-2	8	84	1-5120532-2
8	35.9	34.58	31	5120528-1	8	64	1-5120532-1
7	45.9	44.58	41	5120528-2	8	84	5120532-2
6	35.9	34.58	31	5120528-1	8	64	5120532-1

DIMENSIONS: mm 9 PLC \pm 8 PLC ± 0.03 5 PLC ± 0.003 4 PLC \pm ANGLES \pm FINISH $\pm 30^\circ$		TOLERANCES UNLESS OTHERWISE SPECIFIED: DIMENSIONS: mm 9 PLC \pm 8 PLC ± 0.03 5 PLC ± 0.003 4 PLC \pm ANGLES \pm FINISH $\pm 30^\circ$		DWN B. CARBO 30SEP04 CHK R. WERTZ 30SEP04 APP'D R. WERTZ 30SEP04		tyco Electronics Tyco Electronics Harrisburg, PA 17105-3608	
MATERIAL: SEE TABLE		PRODUCT SPEC: 502-1079 APPLICATION SPEC: 114-25045 WEIGHT: -		NAME: R. WERTZ		PLUG ASSEMBLY, W/ COVER, 1.0mm FH(IEEE1386) CONNECTOR	
CUSTOMER DRAWING		SCALE: 17:1		SHEET: 1 OF 1		REV: B	